

## P-Ch 30V Fast Switching MOSFETs

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

## Product Summary



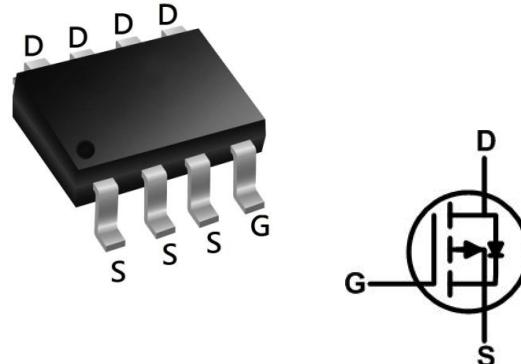
BVDSS	RDSON	ID
-30V	16mΩ	-12.0A

## Description

The XR4435C is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The XR4435C meet the RoHS and Green Product requirement

## SOP8 Pin Configuration



## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D @ T_c = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	-12	A
$I_D @ T_c = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	-7	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	-36	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	25	mJ
$I_{AS}$	Avalanche Current	-10	A
$P_D @ T_c = 25^\circ C$	Total Power Dissipation <sup>4</sup>	3.5	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	48	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	---	°C/W

## P-Ch 30V Fast Switching MOSFETs

Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1\text{mA}$	---	---	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=-9\text{A}$	---	16	21	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=-5\text{A}$	---	21	27	
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-1	-1.6	-2.5	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	---	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSs}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
		$V_{\text{DS}}=-30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=100^\circ\text{C}$	---	---	100	
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=-10\text{V}$ , $I_D=-8\text{A}$	---	42	---	nC
$Q_{\text{gs}}$	Gate-Source Charge		---	8.8	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	7.3	---	
$T_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{GS}}=-10\text{V}$ , $V_{\text{DD}}=-15\text{V}$ , $I_D=-1\text{A}$ , $R_{\text{GEN}}=6\Omega$	---	13	---	ns
$T_r$	Rise Time		---	15	---	
$T_{\text{d(off)}}$	Turn-Off Delay Time		---	198	---	
$T_f$	Fall Time		---	98	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	900	---	pF
$C_{\text{oss}}$	Output Capacitance		---	125	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	109	---	

## Diode Characteristics

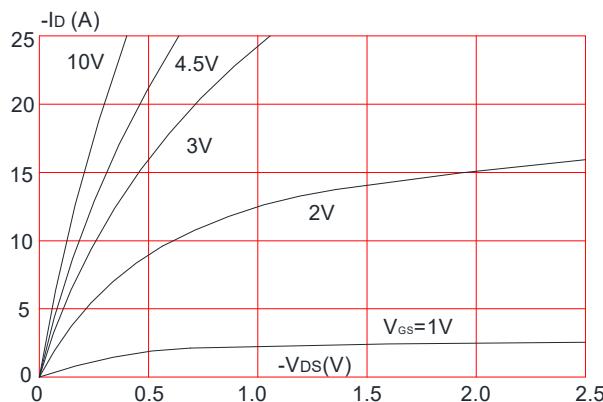
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-12	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-9\text{A}$ , $T_J=25^\circ\text{C}$	---	-0.8	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

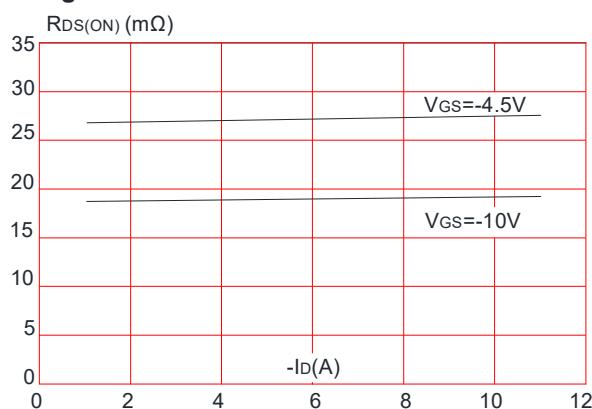
2. EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{\text{DD}}=-15\text{V}$ ,  $V_G=-10\text{V}$ ,  $R_G=25\Omega$ ,  $L=0.5\text{mH}$ ,  $I_{\text{AS}}=-10\text{A}$ 3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 2\%$

## Typical Performance Characteristics

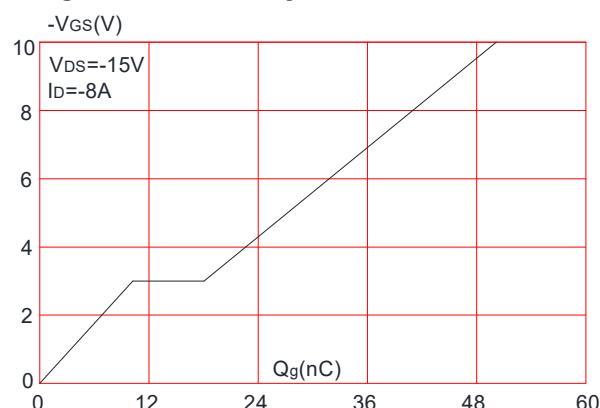
**Figure 1:** Output Characteristics



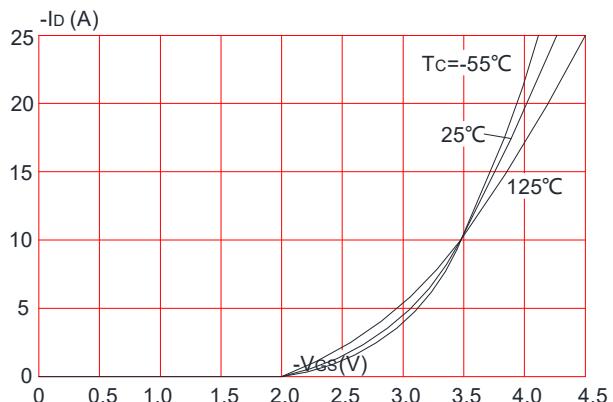
**Figure 3:** On-resistance vs. Drain Current



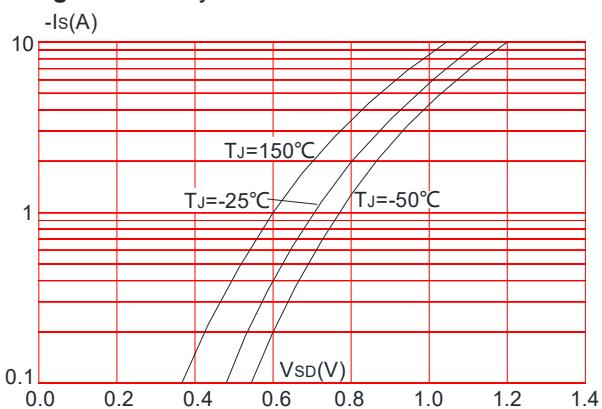
**Figure 5:** Gate Charge Characteristics



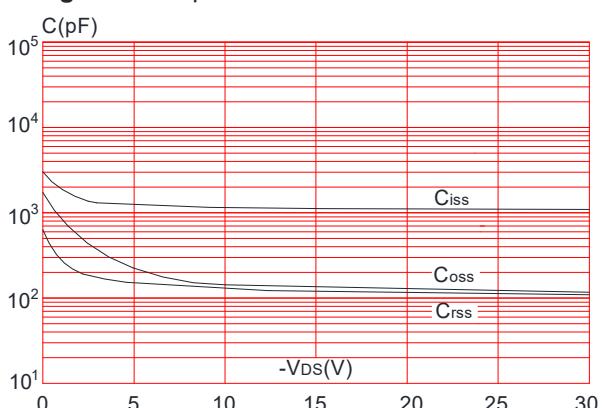
**Figure 2:** Typical Transfer Characteristics



**Figure 4:** Body Diode Characteristics

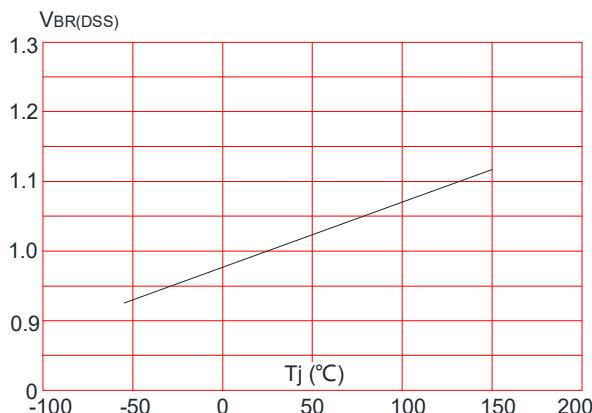


**Figure 6:** Capacitance Characteristics

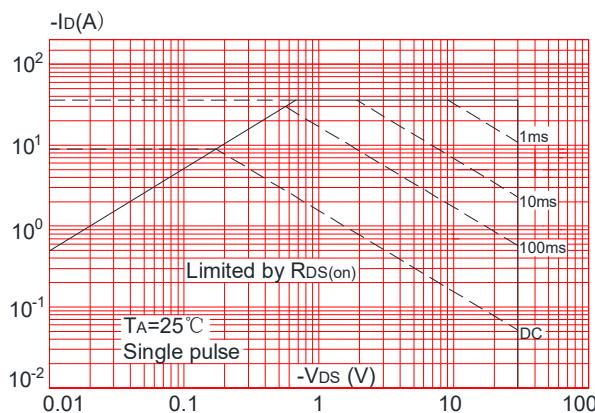


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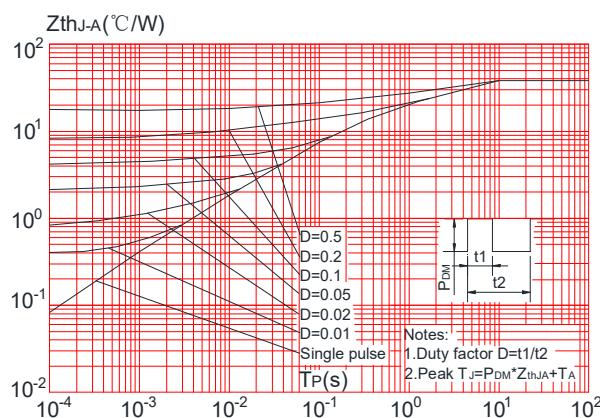
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



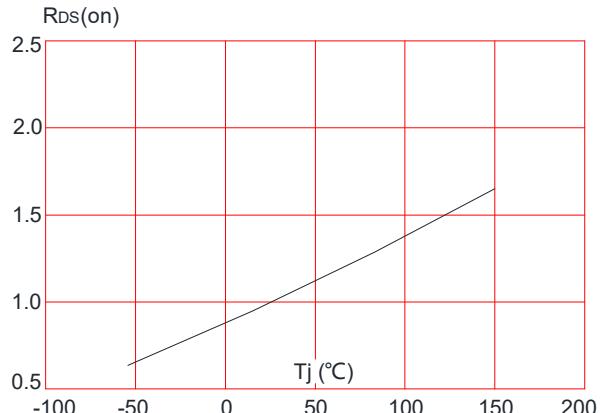
**Figure 9:** Maximum Safe Operating Area



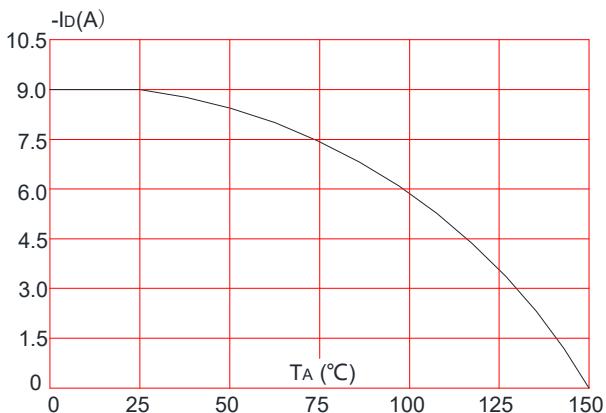
**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



**Figure 8:** Normalized on Resistance vs. Junction Temperature



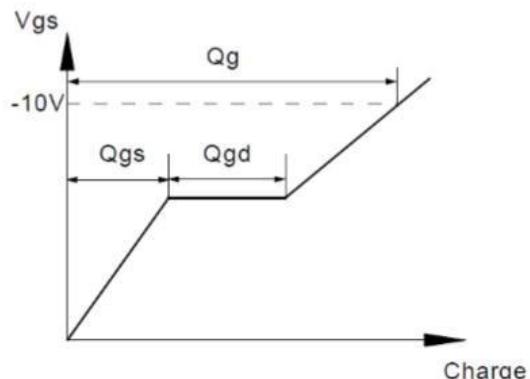
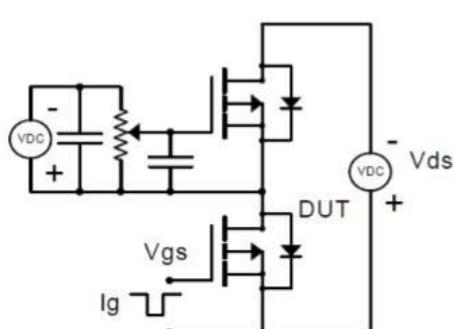
**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



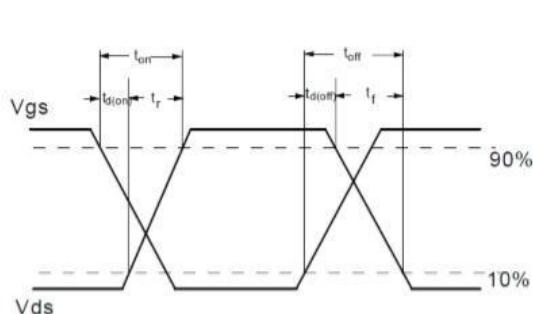
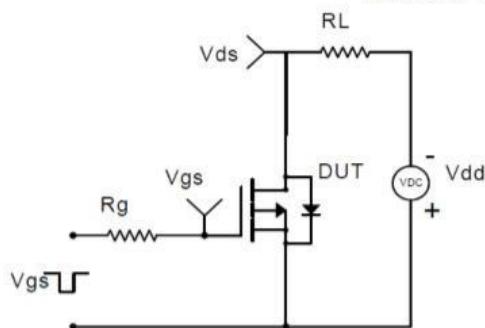
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## Test Circuit

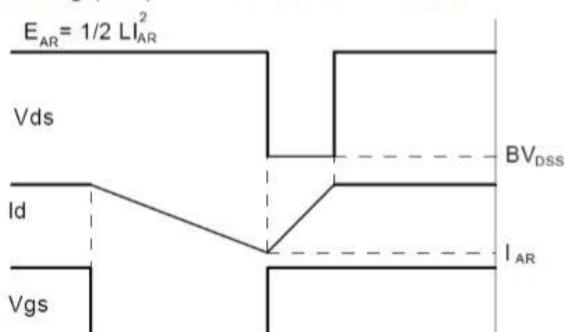
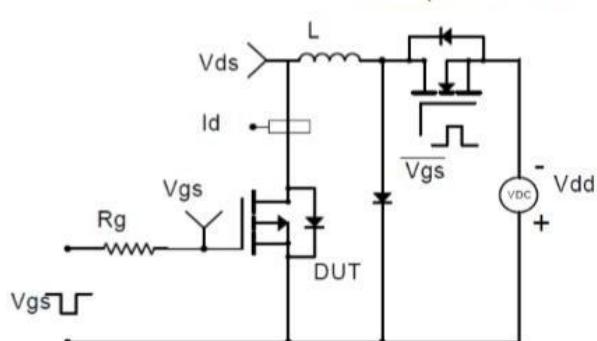
Gate Charge Test Circuit &amp; Waveform



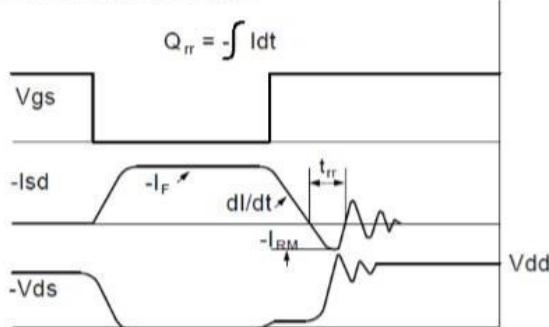
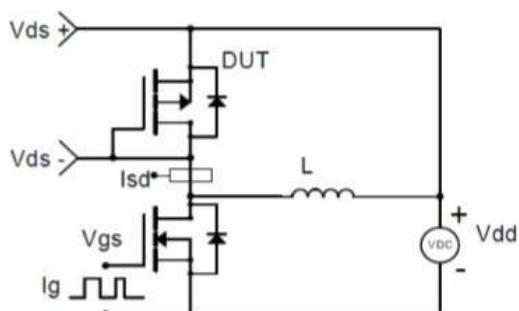
Resistive Switching Test Circuit &amp; Waveforms



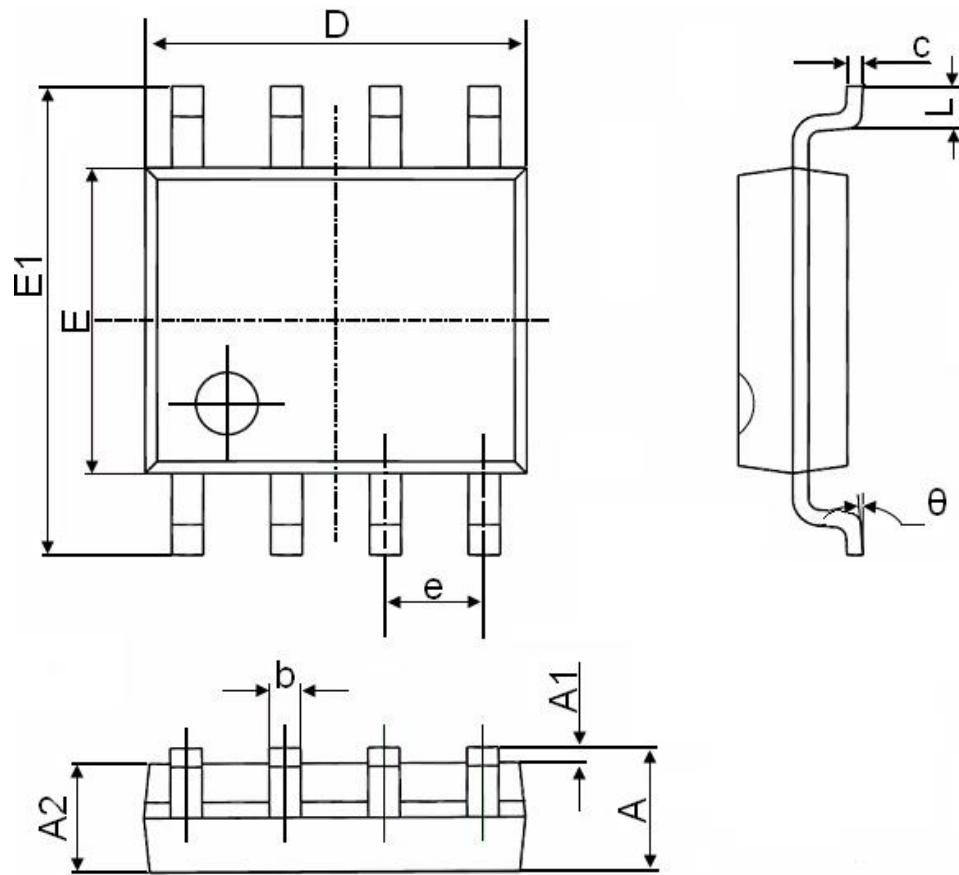
Unclamped Inductive Switching (UIS) Test Circuit &amp; Waveforms



Diode Recovery Test Circuit &amp; Waveforms



## SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°